

# DIN EN 16602-70-12:2016-12 (E)

Space product assurance - Design rules for printed circuit boards; English version  
EN 16602-70-12:2016

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<b>Contents</b>	<b>Page</b>
<b>European foreword</b> .....	<b>12</b>
<b>Introduction</b> .....	<b>13</b>
<b>1 Scope</b> .....	<b>14</b>
<b>2 Normative references</b> .....	<b>15</b>
<b>3 Terms, definitions and abbreviated terms</b> .....	<b>16</b>
3.1 Terms from other standards .....	16
3.2 Terms specific to the present standard .....	16
3.3 Abbreviated terms .....	24
<b>4 Principles</b> .....	<b>26</b>
4.1 Qualified PCBs .....	26
4.2 Manufacturing tolerances .....	26
4.3 Reliability of design .....	26
<b>5 Design review and MRR</b> .....	<b>28</b>
5.1 Overview .....	28
5.2 Documentation .....	28
<b>6 General design and production requirements</b> .....	<b>30</b>
6.1 Reliability of design .....	30
6.2 Choice of materials and build-up.....	30
6.2.1 Overview.....	30
6.2.2 Material selection.....	33
6.3 Selection of the PCB manufacturer .....	33
6.4 Traceability and marking .....	33
<b>7 Rigid PCBs</b> .....	<b>34</b>
7.1 PCB build-up .....	34
7.1.1 General.....	34
7.1.2 Copper styles.....	34
7.1.3 Dielectric thickness.....	36
7.2 PCB dimension.....	39

7.3	Thickness of PCB .....	39
7.3.1	General .....	39
7.3.2	Polyimide PCB .....	40
7.3.3	Epoxy PCB .....	40
7.3.4	Number of copper layers in PCB .....	40
7.3.5	Aspect ratio of vias .....	40
7.4	Track width and spacing .....	41
7.4.1	General .....	41
7.4.2	Manufacturing tolerances for width and spacing .....	41
7.4.3	External layers .....	42
7.4.4	Normal pitch tracks on internal layers .....	43
7.4.5	Fine pitch tracks on internal layers .....	44
7.4.6	Routing to AAD footprint on internal layers .....	45
7.5	Pad design .....	46
7.5.1	Non-functional pad removal .....	46
7.5.2	Pad dimensions .....	46
7.5.3	Non-circular external pads .....	48
7.6	Copper planes in rigid PCB .....	49
7.7	Design considerations for the prevention of sliver and peelable .....	50
7.8	PCB surface finish .....	50
7.8.1	Metallization .....	50
7.8.2	Solder mask .....	51
<b>8</b>	<b>Flex PCBs .....</b>	<b>52</b>
8.1	Overview .....	52
8.2	Dynamic applications .....	52
8.3	PCB build-up .....	52
8.3.1	General .....	52
8.3.2	Dielectric materials .....	52
8.3.3	Copper cladding .....	53
8.3.4	Copper planes in flex PCB .....	53
8.4	Track design .....	54
8.5	Through holes .....	55
8.5.1	Annular ring .....	55
8.5.2	Vias and pads .....	56
8.5.3	Tear drop pad for flex PCB .....	56
8.6	Bending radius .....	57
8.6.1	Overview .....	57
8.6.2	General .....	57

8.7	Sculptured flex PCB .....	58
8.7.1	Overview.....	58
8.7.2	General.....	58
8.7.3	Copper foil dimensions for build-up.....	58
8.7.4	Connection finger .....	59
8.7.5	Through-holes .....	60
8.7.6	Bending radius.....	61
<b>9</b>	<b>Rigid-flex PCBs.....</b>	<b>62</b>
9.1	Overview .....	62
9.2	General.....	62
9.3	Build-up .....	63
9.4	Cover layer .....	64
9.5	Interface of rigid part and flexible part .....	64
9.6	Pads .....	64
<b>10</b>	<b>Thermal rules and heat sinks .....</b>	<b>65</b>
10.1	Overview .....	65
10.2	General requirements.....	65
10.3	Specific requirements for external heat sink .....	65
10.3.1	Overview.....	65
10.3.2	Construction of the interface between PCB and heat sink .....	65
10.3.3	Dimensional requirements.....	66
10.4	Specific requirements for internal heat sink .....	68
10.4.1	General.....	68
10.4.2	Cu thickness and type .....	68
10.4.3	CIC and Molybdenum inserts .....	69
10.4.4	Dimensional requirements.....	69
<b>11</b>	<b>HDI PCBs.....</b>	<b>71</b>
11.1	Overview .....	71
11.2	Justification.....	71
11.3	Microvia technology.....	71
11.4	Microvias .....	72
11.4.1	Build-up of microvia layers .....	72
11.4.2	Design of microvias .....	74
11.4.3	Pad design for microvia .....	74
11.4.4	Annular ring for microvias.....	75
11.5	Core PCB for HDI.....	75
11.5.1	General build-up.....	75

11.5.2	Annular ring on vias for fine pitch footprint .....	76
11.5.3	Track width and spacing on external layers.....	77
11.5.4	Track width and spacing on internal layers for impedance control and routing to AAD .....	77
11.5.5	Track width and spacing on internal layers for differential pair routing within the footprint of 1,0 mm pitch AAD.....	78
11.5.6	Aspect ratio of vias for footprint of AAD with 1 mm pitch.....	79
<b>12</b>	<b>PCBs for high frequency applications.....</b>	<b>81</b>
12.1	Material selection.....	81
12.2	Build-up of RF PCB .....	81
12.3	Embedded film resistors .....	81
12.4	Thickness of RF PCB .....	83
12.5	Track width and spacing.....	83
12.5.1	External layers .....	83
12.5.2	Internal Layers .....	84
12.6	Pad design.....	84
12.6.1	Pad dimensions .....	84
12.6.2	Non-functional pads.....	84
12.7	Surface finish.....	84
12.8	Profiled layers and vias .....	84
<b>13</b>	<b>Electrical requirements for PCB design .....</b>	<b>86</b>
13.1	Overview.....	86
13.2	General.....	87
13.3	PCB drying .....	87
13.4	Electrical characteristics .....	87
13.5	Floating metal .....	88
13.6	Current rating.....	88
13.6.1	Overview.....	88
13.6.2	Requirements for temperature increment.....	89
13.6.3	Requirements for the model IPC-2152 for current rating.....	89
13.6.4	Amendments to the model from IPC-2152 .....	90
13.7	Provisions to prevent open circuit failure on critical tracks .....	91
13.7.1	Overview.....	91
13.7.2	Routing .....	92
13.8	Voltage rating .....	92
13.8.1	Overview.....	92
13.8.2	General requirements.....	92
13.8.3	Spacing on flex and rigid-flex laminate .....	94

13.8.4	Conformal coating .....	95
13.9	Double insulation design rules for critical tracks.....	96
13.9.1	Overview.....	96
13.9.2	Critical nets.....	96
13.9.3	Prevention of short circuit.....	96
13.10	Insulation distance of combined requirements on rigid PCB.....	101
13.11	Controlled impedance tracks.....	106
13.11.1	Definitions specific to controlled impedance.....	106
13.11.2	General rules.....	106
13.11.3	Microstrip and stripline.....	106
13.11.4	Line impedance termination for end-to-end configuration .....	107
13.11.5	Line impedance termination for multidrop configuration.....	107
13.12	Digital PCB.....	108
13.12.1	Overview.....	108
13.12.2	Zone management and routing .....	108
13.12.3	Criticality of digital signals .....	109
13.13	Analog PCB.....	110
13.13.1	Overview.....	110
13.13.2	Criticality of analog signals.....	110
13.13.3	Routing and shielding.....	111
13.14	Mixed analog-digital PCB.....	112
<b>14</b>	<b>Design for assembly.....</b>	<b>113</b>
14.1	Overview .....	113
14.2	General.....	113
14.3	Placement requirements .....	114
14.3.1	Conductive patterns.....	114
14.3.2	Components .....	115
14.3.3	Component pads .....	117
14.3.4	Fan out of SMT pads.....	118
14.3.5	Fan out of PTH .....	120
14.4	Specific requirements for fused tin-lead finish.....	121
14.5	Dimensional requirements for SMT foot print.....	121
14.5.1	Overview.....	121
14.5.2	General.....	122
14.5.3	Bipolar components.....	123
14.5.4	SOIC components .....	124
14.5.5	J-leaded components .....	125
14.5.6	LCC components.....	126

14.5.7	Flat pack components.....	128
14.5.8	AAD components.....	129
<b>15</b>	<b>Design of test coupon .....</b>	<b>130</b>
15.1	Design rules for test coupon.....	130
15.2	Test coupon design .....	130
<b>Annex A</b>	<b>(normative) PCB definition dossier - DRD .....</b>	<b>133</b>
A.1	DRD identification.....	133
A.1.1	Requirement identification and source document.....	133
A.1.2	Purpose and objective .....	133
A.2	Expected response.....	133
A.2.1	Scope and content.....	133
A.2.2	Special remarks .....	139
A.2.3	Example figures .....	139
<b>Annex B</b>	<b>(normative) PCB manufacturing dossier – DRD .....</b>	<b>144</b>
B.1	DRD identification.....	144
B.1.1	Requirement identification and source document.....	144
B.1.2	Purpose and objective .....	144
B.2	Expected response.....	144
B.2.1	Scope and content.....	144
B.2.2	Special remarks .....	145
<b>Annex C</b>	<b>(informative) Example of capability list of PID .....</b>	<b>146</b>
<b>Annex D</b>	<b>(informative) Track current rating computation methodology .....</b>	<b>148</b>
D.1	Introduction of the three models .....	148
D.1.1	Overview.....	148
D.1.2	Formulae for the three models.....	149
D.1.3	Example of current rating.....	150
D.2	Track current rating computation based on IPC-2152.....	150
D.3	Track current rating computation based on CNES/QFT/IN.0113 .....	154
D.4	Track current rating computation based on IPC-2221A .....	158
<b>Annex E</b>	<b>(informative) Example of calculation of PTH pad dimensions .....</b>	<b>162</b>
<b>Annex F</b>	<b>(informative) Prevention of resin starvation and cracks .....</b>	<b>164</b>
F.1	Prevention of resin cracks. ....	164
F.2	Prevention of resin starvation .....	164
<b>Annex G</b>	<b>(informative) Example of MRR checklist.....</b>	<b>166</b>
<b>Bibliography</b>	<b>.....</b>	<b>170</b>

**Figures**

Figure 3-1: Simplified build-up of HDI PCB ..... 20

Figure 3-2: Projected peak-to-peak insulation distance ..... 23

Figure 7-1: Example of automated fine pitch routing and possible improvements ..... 45

Figure 7-2: Comparison between circular and oblong pads showing annular ring and the centre of the hole misregistered with the centre of the pad ..... 48

Figure 7-3: Grid copper plane with openings ..... 49

Figure 7-4: Example of peelable (left) and sliver (right) ..... 50

Figure 8-1: Clearance of tracks on flex PCBs. .... 54

Figure 8-2: Tracks on flex, defining termination and bending zones. .... 55

Figure 8-3: Teardrop reinforcement of terminal pads in flex PCB. .... 56

Figure 8-4: Bending radius of assembled flex ..... 57

Figure 8-5: Sculptured flex circuit..... 58

Figure 8-6: Build-up of sculptured flex circuit ..... 59

Figure 8-7: Connection finger of sculptured flex circuit ..... 60

Figure 8-8 Side view of a component hole for sculptured flex..... 61

Figure 9-1 Example of a build-up of a 6 layer symmetric rigid-flex ..... 62

Figure 10-1: Lay out of heat sink and PCB ..... 67

Figure 10-2: drilling holes and slots in internal heat sink..... 70

Figure 10-3: Angle of intersection of overlapping holes ..... 70

Figure 11-1: Build-up of HDI PCBs with staggered (left) and stacked (right) microvia..... 72

Figure 11-2: Dimple on a microvia ..... 74

Figure 11-3: Tear drop pad design..... 76

Figure 11-4: Example of routing two differential pair tracks between vias in a footprint of an AAD with 1,27 mm pitch. .... 78

Figure 11-5: Example of routing two differential pair tracks between vias in a footprint of an AAD with 1 mm pitch. .... 80

Figure 13-1: Cross section of PCB with insulation distances. .... 87

Figure 13-2: Example of double insulation by increasing distance in X,Y and by not superimposing copper on adjacent layers ..... 100

Figure 13-3: Example of double insulation by increasing distances in X,Y and by using two insulators in Z direction..... 100

Figure 13-4: Edge coupled differential striplines ..... 107

Figure 14-1: Illustration of surface pattern to adjacent surroundings ..... 115

Figure 14-2: Illustration of component placing on PCB w.r.t. adjacent surrounding..... 116

Figure 14-3: Illustration of pad placing on PCB with respect to adjacent surroundings ..... 118

Figure 14-4: Fan out from SMT pad to via ..... 119

Figure 14-5: Example of point symmetric AAD footprint.....	120
Figure 14-6: Track width ( $l_c$ ) ratio to PTH pad (D) diameter. ....	120
Figure 14-7: Track length ( $l_c$ ) between soldering pad of PTH ( $D_1$ ) and via pad ( $D_3$ ).....	121
Figure 14-8: Illustration of bipolar component pads .....	123
Figure 14-9: Illustration of SOIC component pads .....	124
Figure 14-10: Illustration of J-leaded component pads .....	125
Figure 14-11: Illustration of LCC component pads .....	126
Figure 14-12: Illustration of FP and QFP component pads .....	128
Figure 14-13: Illustration of AAD component pads.....	129
Figure A-1 : Example of PCB mechanical layout.....	139
Figure A-2 : Example of a drilling drawing.....	140
Figure A-3 : Example of a table indicating as-designed plated hole diameters.....	141
Figure A-4 : Example of build-up data .....	142
Figure A-5 : Example of the archive file with CRC .....	143
Figure D-1 : Comparison between CNES and IPC-2152 current rating at 5°C increase.....	149
Figure D-2 : IPC-2152: Current rating [A] vs cross sectional area [ $\text{mm}^2$ ] in double log scale.....	151
Figure D-3 : IPC-2152: Track width [mm] vs cross sectional area [ $\text{mm}^2$ ].....	151
Figure D-4 : IPC-2152: Current rating based on Figure D-2, range 0-25 A.....	152
Figure D-5 : IPC-2152: Current rating based on Figure D-2, range 0-10 A.....	152
Figure D-6 : IPC-2152: Current rating based on Figure D-2, range 0-5 A.....	153
Figure D-7 : IPC-2152: Current rating based on Figure D-2, range 0-2 A.....	153
Figure D-8 : CNES/QFT/IN.0113: Current rating [A] vs cross sectional area [ $\text{mm}^2$ ] in double log scale.....	155
Figure D-9 : CNES/QFT/IN.0113: Track width [mm] vs cross sectional area [ $\text{mm}^2$ ].....	155
Figure D-10 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-25 A .....	156
Figure D-11 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-10 A .....	156
Figure D-12 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-5 A .....	157
Figure D-13 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-2 A .....	157
Figure D-14 : IPC-2221A: Current rating [A] vs cross sectional area [ $\text{mm}^2$ ] in double log scale .....	159
Figure D-15 : IPC-2221A: Track width [mm] vs cross sectional area [ $\text{mm}^2$ ].....	159
Figure D-16 : IPC-2221A: Current rating based on Figure D-14, range 0-25 A .....	160
Figure D-17 : IPC-2221A: Current rating based on Figure D-14, range 0-10 A .....	160
Figure D-18 : IPC-2221A: Current rating based on Figure D-14, range 0-5 A .....	161
Figure D-19 : IPC-2221A: Current rating based on Figure D-14, range 0-2 A .....	161
Figure E-1 : PCB manufacturing tolerances for registration and annular ring for HDI PCB .	162
Figure E-2 : PCB manufacturing tolerances for registration and annular ring for rigid-flex sequential PCB .....	163

## Tables

Table 6-1: Characteristics of some example dielectric materials for laminates.....	32
Table 7-1: As-designed versus as-manufactured copper foil thickness .....	36
Table 7-2: Example of worst case as-manufactured insulation distance for laminate with double-sided copper cladding.....	39
Table 7-3: Tolerance on track width and spacing of internal and external layers .....	42
Table 7-4: Minimum as-manufactured track width and spacing for external layers as a function of copper thickness.....	43
Table 7-5: Minimum as-manufactured track width and spacing for internal layers as a function of copper thickness.....	44
Table 8-1: Minimum as-manufactured dimensions of sculptured flex conductor .....	59
Table 12-1: Minimum spacing and width as-designed for RF elements on external layers ...	84
Table 13-1: Legend of terms .....	86
Table 13-2: Current overload limits .....	88
Table 13-3: Minimum insulation distance as function of voltage on as-manufactured PCB for rigid laminate. ....	94
Table 13-4: Minimum insulation distance as function of voltage on as-manufactured PCB for flex laminate.....	95
Table 13-5: Minimum double insulation distance as function of voltage on as-manufactured PCB for rigid laminate.....	98
Table 13-6: Minimum double insulation distance as function of voltage on as-manufactured PCB for flex laminate. ....	98
Table 13-7: Minimum insulation distances on rigid PCB as function of all combined requirements ( <i>part 1 of 4</i> ).....	102
Table 14-1: Minimum distance as-manufactured of the surface pattern to the adjacent surroundings .....	114
Table 14-2: Minimum distance as-manufactured of components to adjacent surroundings	116
Table 14-3: Minimum distance as-manufactured to component pads.....	117
Table 14-4: Minimum track length to component pads .....	120
Table 14-5 Legend for dimensions of components and footprint .....	122
Table 14-6 As-manufactured pad sizes for bipolar components .....	123
Table 14-7: As-manufactured pad sizes for SOIC components .....	124
Table 14-8: As-manufactured pad sizes for J-leaded components .....	125
Table 14-9: As-manufactured pad sizes for LCC components.....	127
Table 14-10: As-manufactured pad sizes for FP and QFP components.....	128
Table 14-11: As-designed pad diameter for AAD components .....	129

Table C-1 : Example of technical capabilities of PCB manufacturer as specified in the PID146